2SC5609

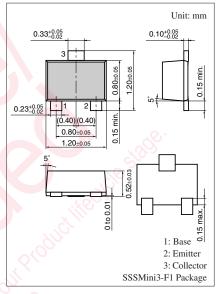
Silicon NPN epitaxial planar type

For general amplification Complementary to 2SA2021

Features

- \bullet High forward current transfer ratio $h_{F\!E}$
- SSS-Mini type package, allowing downsizing and thinning of the equipment and automatic insertion through the tape packing

Absolute Maximum Ratings $T_a = 25^{\circ}C$							
Parameter	Symbol	Rating	Unit				
Collector-base voltage (Emitter open)	V _{CBO}	60	v				
Collector-emitter voltage (Base open)	V _{CEO}	50	V				
Emitter-base voltage (Collector open)	V _{EBO}	7	v				
Collector current	I _C	100	mA				
Peak collector current	I _{CP}	200	mA				
Collector power dissipation	P _C	100	mW				
Junction temperature	Tj	125	°C				
Storage temperature	T _{stg}	-55 to +125	°CO				



Marking Symbol: 3F

Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emitter open)	V _{CBO}	$I_{\rm C} = 10 \ \mu A, I_{\rm E} = 0$	60	Se la		V
Collector-emitter voltage (Base open)	V _{CEO}	$I_C = 2 \text{ mA}, I_B = 0$	50			V
Emitter-base voltage (Collector open)	V _{EBO}	$I_{\rm E} = 10 \ \mu A, I_{\rm C} = 0$	7			V
Collector-base cutoff current (Emitter open)	I _{CBO}	$V_{CB} = 20 \text{ V}, I_E = 0$			0.1	μΑ
Collector-emitter cutoff current (Base open)	I _{CEO}	$V_{CE} = 10 \text{ V}, I_B = 0$			100	μΑ
Forward current transfer ratio	h _{FE1}	$V_{CE} = 10 \text{ V}, \text{ I}_{C} = 2 \text{ mA}$	180		390	
	h _{FE2}	$V_{CE} = 2 V, I_C = 100 mA$	90			—
Collector-emitter saturation voltage	V _{CE(sat)}	$I_{\rm C} = 100 \text{ mA}, I_{\rm B} = 10 \text{ mA}$		0.1	0.3	V
Transition frequency	f _T	$V_{CB} = 10 \text{ V}, I_E = -2 \text{ mA}, f = 200 \text{ MHz}$		80		MHz
Collector output capacitance	C _{ob}	$V_{CB} = 10 \text{ V}, I_E = 0, f = 1 \text{ MHz}$		3.5		pF
(Common base, input open circuited)						

Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

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